



FZT600 / FZT600B

140V NPN DARLINGTON TRANSISTOR IN SOT223

Features

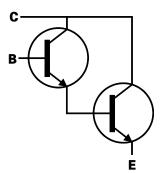
- BV_{CEO} > 140V
- BV_{CBO} > 160V
- I_C = 2A High Continuous Current
- NPN Darlington with Gain >10k
- Guaranteed hFE Specified up to 1A
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

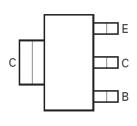
- Case: SOT223
- Case Material: Molded Plastic. "Green" Molding Compound;
 UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 [®]
- Weight: 0.112 grams (Approximate)







Device Symbol



Top View Pin-Out

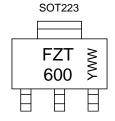
Ordering Information (Notes 4 & 5)

| Product | Compliance | Marking | Reel size (inches) | Tape width (mm) | Quantity per reel |
|------------|------------|---------|--------------------|-----------------|-------------------|
| FZT600TA | AEC-Q101 | FZT600 | 7 | 12 | 1,000 |
| FZT600BTA | AEC-Q101 | FZT600B | 7 | 12 | 1,000 |
| FZT600BQTA | Automotive | FZT600B | 7 | 12 | 1,000 |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally
 the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_compliance_definitions/.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



FZT 600 = Product Type Marking Code (Group A) FZT 600B = Product Type Marking Code (Group B) $Y\overline{W}W$ = Date Code Marking Y or \overline{Y} = Last Digit of Year (ex: 5= 2015) WW or WW = Week Code (01~53)



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|------------------------------|-----------------|-------|------|
| Collector-Base Voltage | V_{CBO} | 160 | V |
| Collector-Emitter Voltage | $V_{\sf CEO}$ | 140 | V |
| Emitter-Base Voltage | V_{EBO} | 10 | V |
| Continuous Collector Current | Ic | 2 | Α |
| Peak Pulse Current | I _{CM} | 4 | Α |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | | |
|---|-----------------------------------|----------------|------|------|--|
| | (Note 6) | | 3.0 | | |
| Power Dissipation | (Note 7) | Ь | 2.0 | W | |
| Power Dissipation | (Note 8) | P _D | 1.6 | | |
| | (Note 9) | | 1.2 | | |
| | (Note 6) | | 41.7 | | |
| Thermal Resistance, Junction to Ambient | (Note 7) | Б | 62.5 | | |
| Thermal Resistance, Junction to Ambient | (Note 8) | $R_{	hetaJA}$ | 78.1 | °C/W | |
| | (Note 9) | | 104 | | |
| Thermal Resistance Junction to Lead (Note 10) | | $R_{	hetaJL}$ | 12.9 | | |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C | | |

ESD Ratings (Note 11)

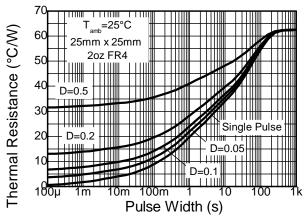
| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 2,000 | V | 2 |
| Electrostatic Discharge - Machine Model | ESD MM | 200 | V | В |

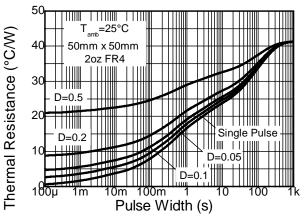
Notes:

- 6. For a device mounted with the collector lead on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 7. Same as Note 6, except the device is mounted on 25mm x 25mm 2oz copper.
- 8. Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
- 9. Same as Note 6, except the device is mounted on minimum recommended pad layout.
- 10. Thermal resistance from junction to solder-point (at the end of the collector lead).
- 11. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



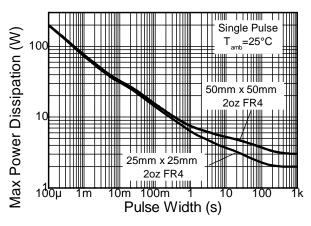
Thermal Characteristics and Derating Information

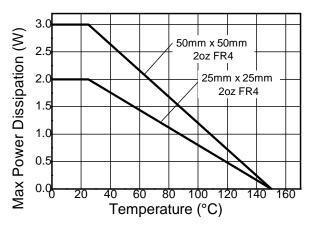




Transient Thermal Impedance







Pulse Power Dissipation

Derating Curve



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

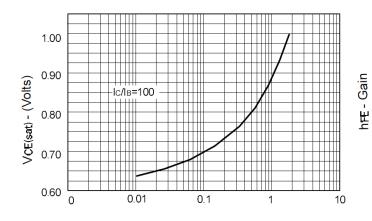
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|--|----------------------|--------------------------|----------------------------|-----------------|----------|---|
| Collector-Base Breakdown Voltage | BV _{CBO} | 160 | _ | _ | V | I _C = 100μA |
| Collector-Emitter Breakdown Voltage (Note 12) | BV _{CEO} | 140 | _ | _ | V | I _C = 10mA |
| Emitter-Base Breakdown Voltage | BV _{EBO} | 10 | _ | _ | V | I _E = 100μA |
| Collector-Base Cut-Off Current | I _{CBO} | _ | _ | 0.01 10 | μA μA | V _{CB} = 140V V _{CB} = 140V, T _A = +100°C |
| Collector-Emitter Cut-Off Current | Ices | - | _ | 10 | μΑ | V _{CES} = 140V |
| Emitter Cut-Off Current | I _{EBO} | - | _ | 0.1 | μΑ | V _{EB} = 8V |
| Group A (FZT600) DC Current Gain (Note 12) | h | 1,000 2,000 1,000 | 1 1 1 | 100,000 | ı | $I_C = 50$ mA, $V_{CE} = 10$ V $I_C = 500$ mA, $V_{CE} = 10$ V $I_C = 1$ A, $V_{CE} = 10$ V |
| Group B (FZT600B) | hfE | 5,000 10,000 5,000 | 10,000 20,000 10,000 | 100,000 — | - | $I_C = 50$ mA, $V_{CE} = 10$ V $I_C = 500$ mA, $V_{CE} = 10$ V $I_C = 1$ A, $V_{CE} = 10$ V |
| Collector-Emitter Saturation Voltage (Note 12) | V _{CE(sat)} | _ | 0.75 0.85 | 1.1 1.2 | V | $I_C = 500 \text{mA}, I_B = 5 \text{mA}$ $I_C = 1 \text{A}, I_B = 10 \text{mA}$ |
| Base-Emitter Saturation Voltage (Note 12) | V _{BE(sat)} | _ | 1.7 | 1.9 | V | I _C = 1A, I _B = 10mA |
| Base-Emitter Turn-On Voltage (Note 12) | V _{BE(on)} | _ | 1.5 | 1.7 | V | I _C = 1A, V _{CE} = 5V |
| Output Capacitance (Note 12) | C _{obo} | _ | 10 | 15 | pF | V _{CB} = 10V, f = 1MHz |
| Current Gain-Bandwidth Product (Note 12) | f⊤ | 150 | 250 | _ | MHz | V _{CE} = 10V, I _C = 100mA, f=20MHz |
| Turn-On Time | t _{on} | _ | 0.75 | _ | μs | $V_{CC} = 10V, I_C = 500mA$ |
| Turn-Off Time | t _{off} | _ | 2.20 | _ | μs | $I_{B1} = -I_{B2} = 0.5 \text{mA}$ |

4 of 7

Note: 12. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



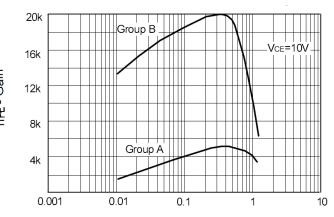
Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



Ic - Collector Current (Amps)

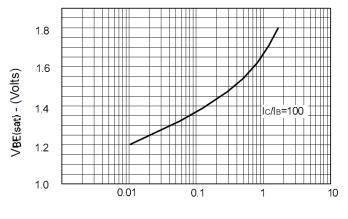
B

VCE(sat) v IC



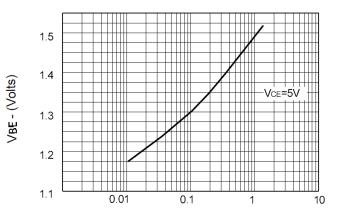
Ic - Collector Current (Amps)

hFE v IC



Ic - Collector Current (Amps)

VBE(sat) v IC



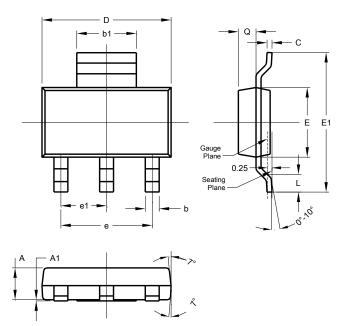
Ic - Collector Current (Amps)

VBE(on) v IC



Package Outline Dimensions

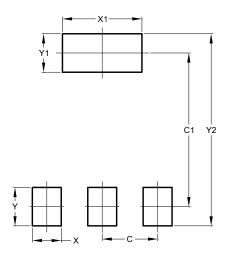
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



| SOT223 | | | | |
|----------------------|-------|------|------|--|
| Dim | Min | Max | Тур | |
| Α | 1.55 | 1.65 | 1.60 | |
| A1 | 0.010 | 0.15 | 0.05 | |
| b | 0.60 | 0.80 | 0.70 | |
| b1 | 2.90 | 3.10 | 3.00 | |
| С | 0.20 | 0.30 | 0.25 | |
| D | 6.45 | 6.55 | 6.50 | |
| Е | 3.45 | 3.55 | 3.50 | |
| E1 | 6.90 | 7.10 | 7.00 | |
| е | - | - | 4.60 | |
| e1 | - | - | 2.30 | |
| L | 0.85 | 1.05 | 0.95 | |
| Q | 0.84 | 0.94 | 0.89 | |
| All Dimensions in mm | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 2.30 |
| C1 | 6.40 |
| Х | 1.20 |
| X1 | 3.30 |
| Y | 1.60 |
| Y1 | 1.60 |
| Y2 | 8.00 |

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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